In the Claims:

Please amend the claims to read as indicated in the following list of claims:

- 1. [Currently amended] A fusible resistor, comprising:
 - a resistor body;

a fusible element layer, which surrounds the resistor body and is fusible when a current over a predetermined current value is applied to the resistor body, the fusible element layer comprising a material having a temperature coefficient of over 2,000 ppm/°C and a resistivity of 1×10^{-8} to $50 \times 10^{-8} \Omega \cdot m$ (ohm/meter);

caps, which surround ends of the fusible element layer; lead wires, which are attached to the caps; and an insulating layer for insulating the fusible element layer and the caps.

- 2. [Original] The fusible resistor of Claim 1, wherein the fusible element layer further comprises at least copper.
- 3. Cancelled.
- 4. [Original] The fusible resistor of Claim 1, further comprising an anti-oxidation layer, which surrounds the fusible element layer.
- 5. [Original] The fusible resistor of Claim 4, wherein the anti-oxidation layer further comprises at least a silver paste.
- 6. [Previously presented] The fusible resistor of Claim 1, further comprising a conductive layer, which is formed between the resistor body and the fusible element layer and made of a conductive material.

Response to Official Action Dated 19 September 2006

Re: USSN 10/519,692

Page 4

7. [Currently amended] The fusible resistor of Claim [[4]] 6, wherein the conductive

layer further comprises at least nickel and chrome.

8. [Currently amended] The fusible resistor of Claim 6, further comprising a groove,

which is formed through the fusible element layer, the an anti-oxidation layer associated

with the fusible element layer, and the conductive layer to reach the resistor body.

9. [Original] The fusible resistor of Claim 8, wherein the groove is in the form of a

spiral along a circumference of the fusible resistor.

10. [Currently amended] A method of fabricating a fusible resistor, comprising the

steps of:

preparing a resistor body;

forming a fusible element layer, which surrounds the resistor body and is

fusible when a current over a predetermined current value is applied to the resistor body,

the fusible element comprising a material having a temperature coefficient of over 2,000

ppm/°C and a resistivity of 1×10^{-8} to $50 \times 10^{-8} \Omega \cdot m$ (ohm/meter);

forming caps, which surround ends of the fusible element layer;

forming lead wires, which are attached to the caps; and

forming an insulating layer for insulating the fusible element layer and the

caps.

11. [Original] The method of Claim 10, wherein the fusible element layer further

comprises at least copper.

12. Cancelled.

13. [Original] The method of Claim 10, further comprising a step of forming an anti-

oxidation layer, which surrounds the fusible element layer.

Response to Official Action Dated 19 September 2006

Re: USSN 10/519,692

Page 5

14. [Original] The method of Claim 13, wherein the anti-oxidation layer further

comprises at least a silver paste.

15. [Previously presented] The method of Claim 10, further comprising a step of

forming a conductive layer, which is formed between the resistor body and the fusible

element layer and made of a conductive material.

16. [Original] The method of Claim 15, wherein the conductive layer further comprises

at least nickel and chrome.

17. [Currently amended] The method of Claim 15, further comprising a step of

forming a groove, which is formed through the fusible element layer, the an anti-

oxidation layer associated with the fusible element layer, and the conductive layer to

reach the resistor body.

18. [Original] The method of Claim 17, wherein the groove is in the form of a spiral

along a circumference of the fusible resistor.

19. [Previously presented] The fusible resistor of Claim 4, further comprising

a conductive layer, which is formed between the resistor body and the fusible

element layer and made of a conductive material.

20. [Currently amended] The method of Claim 13, further comprising a step of:

forming a conductive layer, which is formed between the resistor body and the

fusible element layer and made of a conductive material.